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Interested committees:

Title: BS IEC 63215-4 Endurance test methods for die attach materials applied to power electronic devices

Part 4: Power cycling test method and reliability performance index for Die attach materials (Near Chip Interconnection) applied to module type power electronic devices

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- ii) affects other national standard(s)
- iii) requires additional national guidance or information

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

For national standards, comments will be reviewed by the relevant UK national committee and the resulting standards published as a British Standard.

UK Vote

Please indicate whether you consider the UK should submit a negative (with supporting technical reasons) or positive vote on this draft. Please indicate if you are aware of any reason why this draft standard should not be published as a British Standard.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



91/1822/CD

COMMITTEE DRAFT (CD)

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CLOSING DATE FOR COMMENTS:
2023-01-20

SUPERSEDES DOCUMENTS:
91/1497/NP, 91/1529A/RVN

IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY	
SECRETARIAT: Japan	SECRETARY: Mr Masahide Okamoto
OF INTEREST TO THE FOLLOWING COMMITTEES: TC 22,TC 47	PROPOSED HORIZONTAL STANDARD: ☐ Other TC/SCs are requested to indicate their interest, if any, in this CD to the secretary.
FUNCTIONS CONCERNED: ☐ EMC ☐ ENVIRONMENT ☐ QUALITY ASSURANCE ☐ SAFETY	

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Recipients of this document are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

TITLE:

Endurance test methods for die attach materials – Part 4: Power cycling test method for die attach materials (near chip interconnection) applied to module type power electronic devices

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENDURANCE TEST METHODS FOR DIE ATTACH MATERIALS

Part 4: Power cycling test method for die attach materials (near chip interconnection) applied to module type power electronic devices

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IEC 63215-4 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/XX/FDIS	91/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 63215 series, published under the general title *ENDURANCE TEST METHODS FOR DIE ATTACH MATERIALS*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

The National Committees are requested to note that for this document the stability date is 20XX..

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